

- ★ Super Low  $R_{DS(ON)}$
- ★ Green Device Available
- ★ Advanced Trench technology

### Product Summary

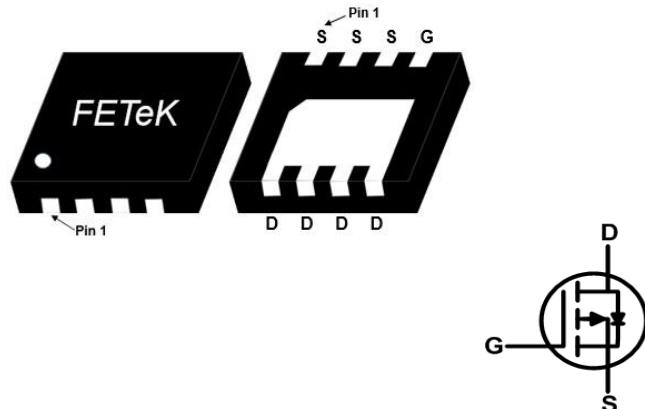


BVDSS	RDS(on)	ID
-20V	5mΩ	-50A

### Description

The FKCE2631 is the advanced trench P-ch MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery

### DFN3.3x3.3 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current <sup>1</sup>	-50	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current <sup>1</sup>	-39	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-200	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	80	mJ
$I_{AS}$	Avalanche Current	40	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>4</sup>	83	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup> ( $t \leq 10S$ )	---	20	°C/W
	Thermal Resistance Junction-ambient <sup>1</sup> (Steady State)	---	55	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-case <sup>1</sup>	---	1.5	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

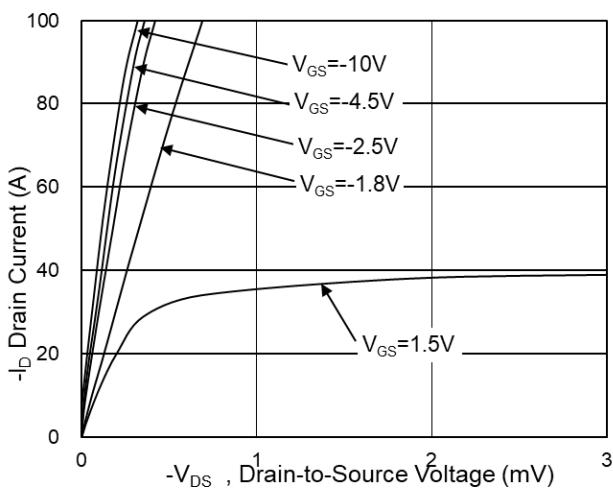
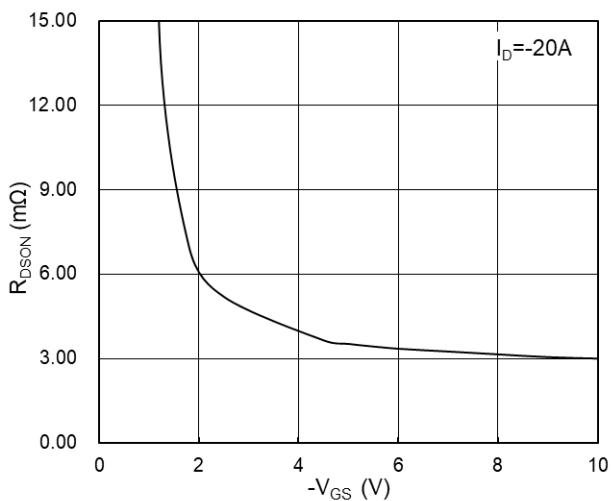
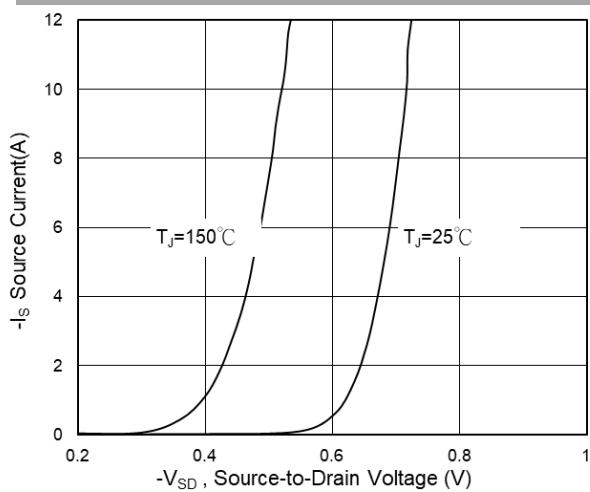
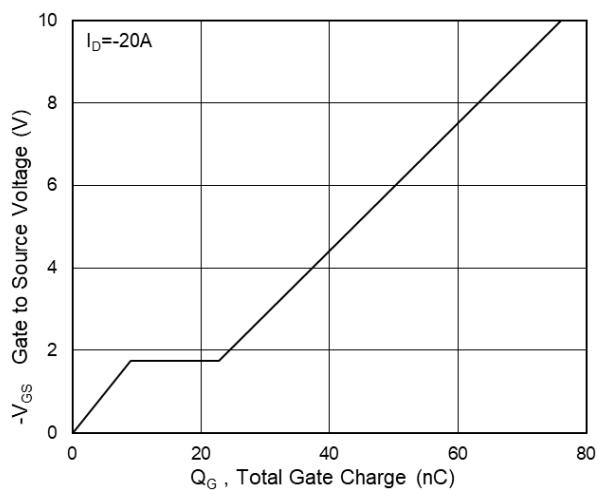
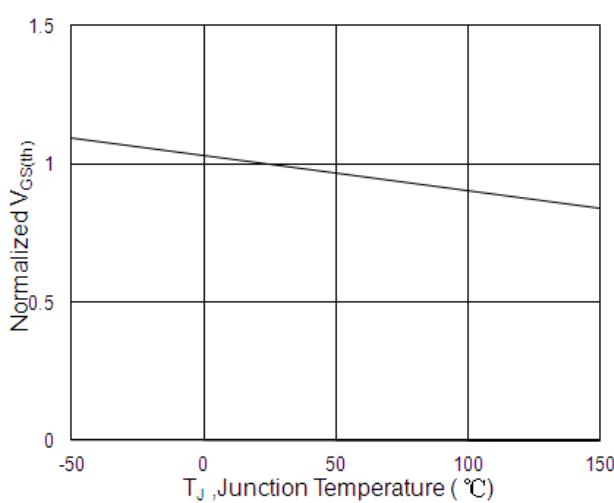
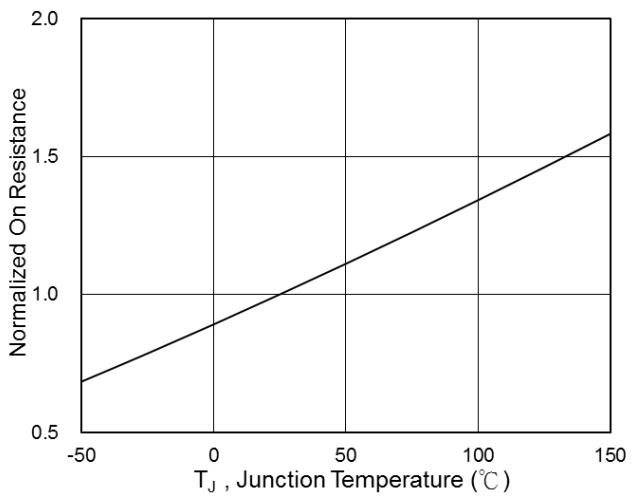
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-20\text{A}$	---	3.6	5	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$ , $I_D=-20\text{A}$	---	4.7	6.5	$\text{m}\Omega$
		$V_{\text{GS}}=-1.8\text{V}$ , $I_D=-20\text{A}$	---	6.4	8.5	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-0.35	-0.5	-1.0	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	uA
		$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	5	---	$\Omega$
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-20\text{A}$	---	76	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	9	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	13.7	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3\Omega$ , $I_D=-20\text{A}$	---	12	---	ns
$T_r$	Rise Time		---	10.7	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	55.4	---	
$T_f$	Fall Time		---	15.2	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	4307	---	pF
$C_{\text{oss}}$	Output Capacitance		---	501	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	321	---	

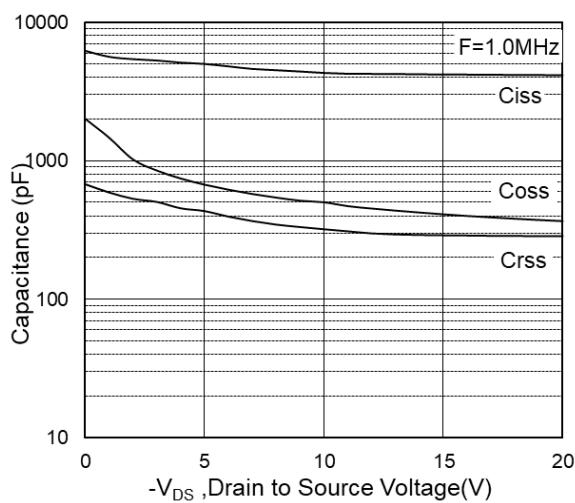
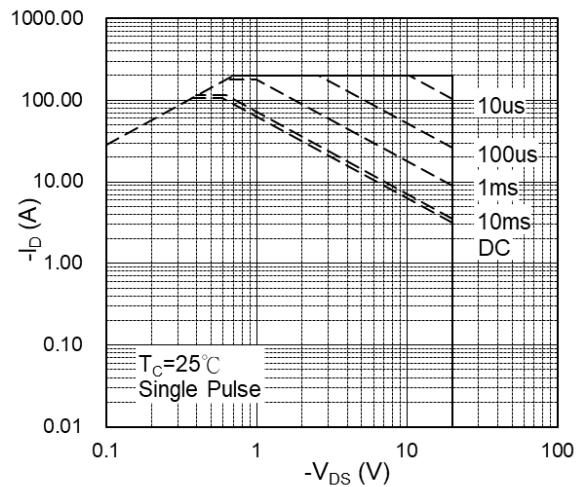
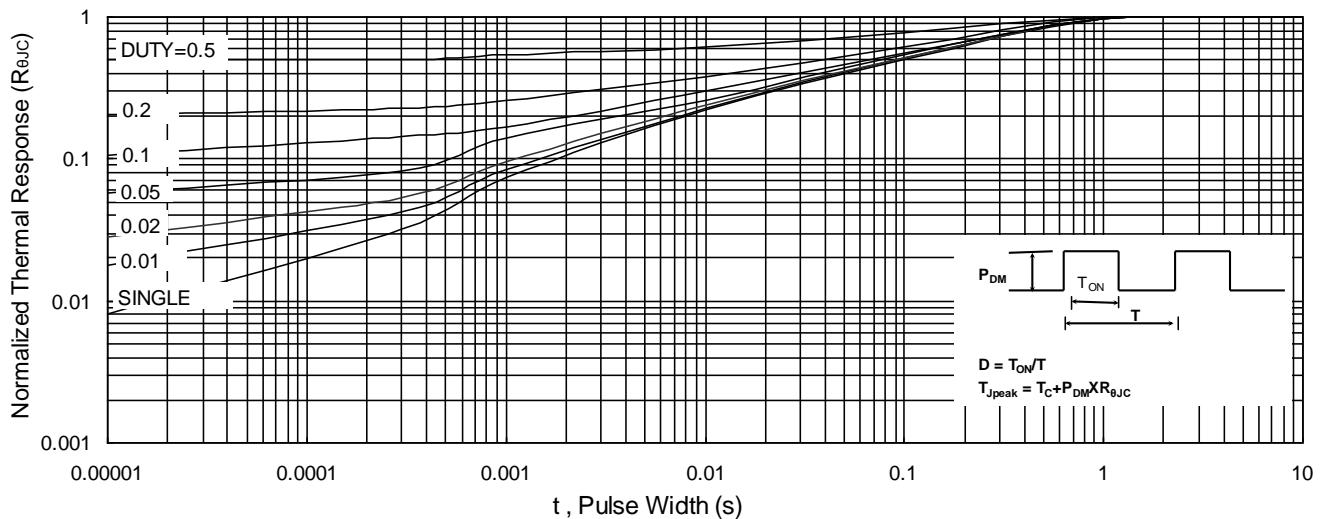
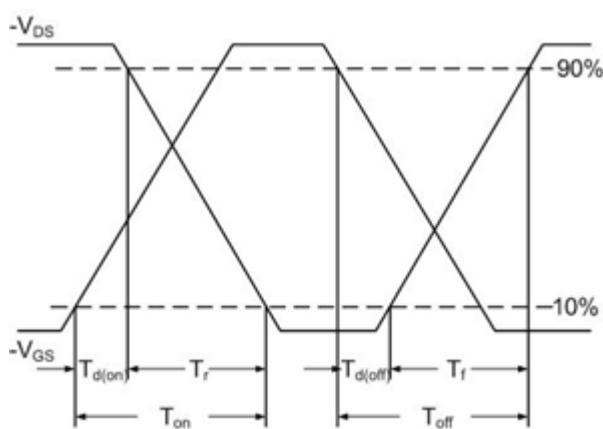
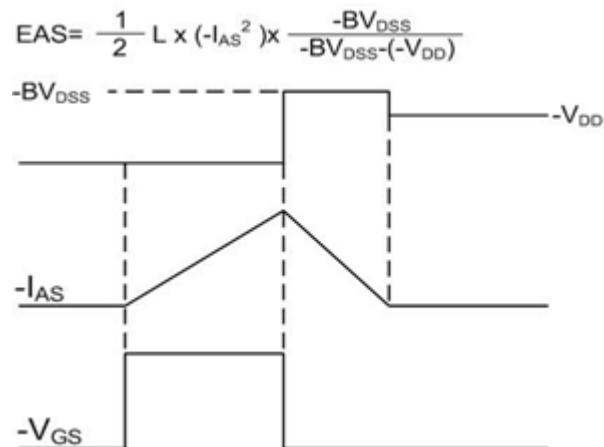
## Diode Characteristics

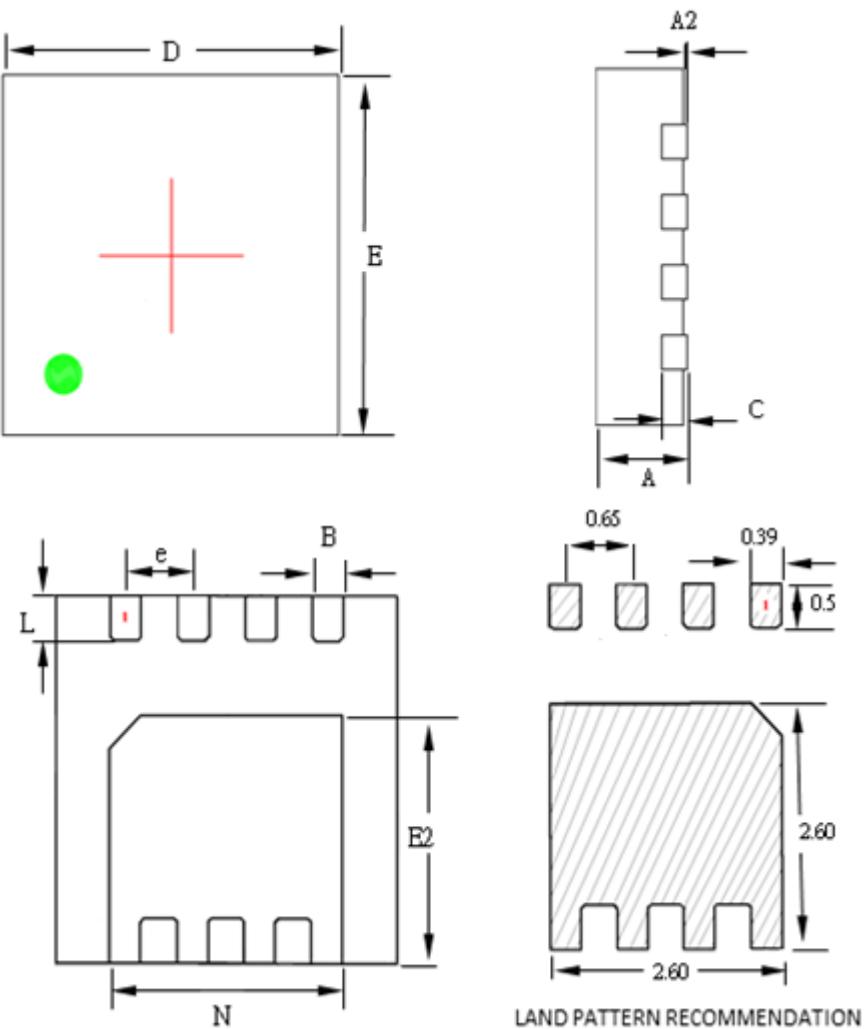
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-50	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=-20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	55	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	365	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-25\text{V}$ ,  $V_{\text{GS}}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=-40\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.3 Source Drain Forward Characteristics**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

**DFN3.3x3.3 8L Outline**


SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031
A2	0.00	--	0.05	0.000	--	0.002
B	0.24	0.30	0.35	0.009	0.012	0.014
C	0.10	0.15	0.25	0.004	0.006	0.010
D	3.15	3.30	3.40	0.124	0.130	0.134
E	3.15	3.30	3.40	0.124	0.130	0.134
E2	2.15	2.25	2.35	0.085	0.089	0.093
L	0.35	0.40	0.45	0.014	0.016	0.018
N	2.10	2.25	2.35	0.083	0.089	0.093
e	--	0.65	--	--	0.026	--